

# TEM96B

## Thermal Conductive RF Absorber Pad

LiPOLY TEM96B is a thermally conductive absorber based upon soft magnetic materials dispersed in a polymeric resin. It has a thermal conductivity of 3.0 W/m\*K and dissipates electromagnetic radiation rapidly to mitigate against EMI issues.

### FEATURES

- / Thermal conductivity: 3.0 W/m\*K
- / Excellent absorption characteristics
- / Naturally tacky
- / Reworkable

### TYPICAL APPLICATION

- / IC, CPU, MOS, LED, M/B, Heat sink
- / LCD-TV, Notebook PC, PC, Telecom device, Wireless hub
- / DDR II module, DVD applications, Hand-set applications
- / 5G base station & infrastructure
- / EV electric vehicle

### SPECIFICATIONS

- / Sheet form
- / Die-cut parts

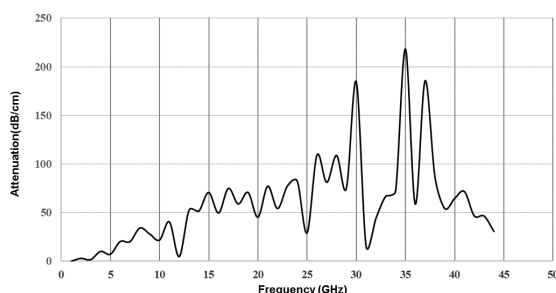
### FREQUENCY APPLICATION

- 2.4 GHz Wi-Fi Router , Bluetooth
- 3.5 GHz 5G Mobile Networks
- 5.0 GHz Wi-Fi Router
- 12~18 GHz Low Earth Orbit (LEO) System
- 28 GHz 5G Mobile Networks
- 39 GHz 5G Mobile Networks

### TYPICAL PROPERTIES

PROPERTY	TEM96B	TEST METHOD	UNIT
Color	Dark Gray	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	3.9	ASTM D792	g/cm <sup>3</sup>
Hardness	45	ASTM D2240	Shore OO
TML	0.07	By LiPOLY	%
Water absorption	0.04	ASTM D570	%
Application temperature	-60~180	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	7	ASTM D5470 modify	%
Deflection @20 psi	12	ASTM D5470 modify	%
Deflection @30 psi	16	ASTM D5470 modify	%
Deflection @40 psi	21	ASTM D5470 modify	%
Deflection @50 psi	25	ASTM D5470 modify	%
EMI Attenuation @1.0mm			
EMI attenuation@ 2.4 GHz	7.0	ASTM D4935 modify	dB/cm
EMI attenuation@ 3.5 GHz	8.6	ASTM D4935 modify	dB/cm
EMI attenuation@ 5.0 GHz	20.3	ASTM D4935 modify	dB/cm
EMI attenuation@ 12 GHz	52.5	ASTM D4935 modify	dB/cm
EMI attenuation@ 18 GHz	70.8	ASTM D4935 modify	dB/cm
EMI attenuation@ 28 GHz	75.0	ASTM D4935 modify	dB/cm
EMI attenuation@ 39 GHz	64.4	ASTM D4935 modify	dB/cm
ELECTRICAL			
Surface resistivity	>10 <sup>11</sup>	ASTM D257	Ohm
Volume resistivity	>10 <sup>10</sup>	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	3.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.634	ASTM D5470	°C-in <sup>2</sup> / W
Thermal impedance@20 psi	0.606	ASTM D5470	°C-in <sup>2</sup> / W
Thermal impedance@30 psi	0.579	ASTM D5470	°C-in <sup>2</sup> / W
Thermal impedance@40 psi	0.551	ASTM D5470	°C-in <sup>2</sup> / W
Thermal impedance@50 psi	0.516	ASTM D5470	°C-in <sup>2</sup> / W

### Attenuation



### Thermal Resistance vs. Pressure vs. Deflection

